

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-4. (Canceled)

5. (Currently amended) A digital circuitry system comprising:

a memory module having a plurality of stackable cross-point memory arrays stacked so as to have interconnection in a unitary package; and

a plurality of conductive pads, ~~said conductive pads adapted for providing said~~ adapted to provide the interconnection of ~~said the plurality of~~ stacked cross-point memory arrays through a patterned waffle structure.

6. (Currently amended) The digital circuitry system as claimed in claim 5, where ~~in said~~ the patterned waffle structure of ~~said the~~ conductive pads is formed from at least two separately patterned groupings of layered materials which are combined together, in substantially the same planar direction, at a substantially orthogonal juxtaposition.

7. (Currently amended) The digital circuitry system as claimed in claim 6, where ~~in said~~ the at least two separately patterned groupings of layered materials are formed from the application of at least one thin film on a flexible substrate.

8. (New) The digital circuitry system as claimed in claim 6, where the patterned waffle structure represents a large circuit element in proximity to a small circuit element

9. (New) The digital circuitry system as claimed in claim 8, where a diameter of at least one of the conductive pads is greater than 100 microns

10. (New) The digital circuitry system as claimed in claim 8, where a size ratio of the large circuit element to the small circuit element is at least 10 to 1.

11. (New) The digital circuitry system as claimed in claim 8, where a width of the small circuit element is represented by a variable “d” and where a waffle pattern of the large circuit element is created by subdividing an area of the large circuit element into sections having a width equal to “d”.

12. (New) The digital circuitry system as claimed in claim 11, where the sections of the large circuit element waffle pattern have a length equal to “d”.

13. (New) The digital circuitry system as claimed in claim 8, where the large circuit element is at least one of a pixel, a bond pad, and a capacitor.

14. (New) The digital circuitry system as claimed in claim 8, where the small circuit element is at least one of a transistor, a resistor, and a line.